



REV A 10/15/09 JDB

NOTES: MATERIALS; MANUFACTURE TO MEET EU RoHS DIRECTIVE. ALL MATERIAL, (INCLUDING SOLDERMASK) REFER TO EU RoHS DIRECTIVE 20002/95/EC. LAMINATE & RESIN MATERIALS; Tg>170C. Td>310c ACCEPTABLE MATERIALS; ISOLA 370HR' NELCO N40000-29, ISOLA IS410, FR4-08

CLADDING; EXTERNAL LAYERS OVERPLATE TO 1 1/2 OZ COPPER. INTERNAL PLANE LAYERS 1 OZ. COPPER.

SOLDER MASK; SHALL BE BLUE LIQUID PHOTOIMAGABLE (LPI) APPLIED ON BOTH SIDES OVER BARE COPPER AND SHALL MEET IPC-SM-840 (LATEST REV.) CLASS 3.

SILK SCREEN; SHALL BE PERMANENT NON-CONDUCTIVE EPOXY INK, COLOR WHITE.

U.L. RATING; 94VO MINIMUM.

FINISH; HARD GOLD.

FABRICATION:

- REFER TO IPC-4101B/99 SERIES (LATEST REV.), CLASS 2 FOR FABRICATION UNLESS OTHERWISE SPECIFIED.
- UNDIMENSIONED HOLES TO BE LOCATED WITHIN +/- .005 OF THEIR TRUE POSITION WITH RESPECT TO ARTWORK.
- PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN .001 INCH MINIMUM AVERAGE, WITH NO READING LESS THAN .0008 BY CROSS SECTION.
- HOLE DIAMETERS APPLY AFTER PLATING.
- FINISHED CONDUCTOR WIDTHS SHALL NOT BE REDUCED FROM THE NOMINAL, INDICATED ON THE MASTER PATTERN, BY MORE THAN THE CONDUCTOR THICKNESS.
- MINIMUM DESIGN LINE WIDTH IS .005 INCH.
- MINIMUM DESIGN SPACING IS .005 INCH.
- BOARD/PANEL MUST MEET IPC-A-600 (LATEST REV.) CLASS 2 FOR FLATNESS.
- MFGR. TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK ON SECONDARY SIDE IN A CLEAR AREA UNLESS OTHERWISE INDICATED;
- NON-FUNCTIONAL PADS MAY BE REMOVED FROM INNER SIGNAL LAYERS AT MFGR. DISCRETION.
- IF PAD SIZES PROVIDED ARE NOT LARGE ENOUGH TO MAINTAIN ANNULAR RING REQUIREMENT, MFGR. MAY TEAR DROP PADS TO MAINTAIN ANNULAR RING AT PAD TO CIRCUIT INTERFACE ONLY AND MUST INSURE ELECTRICAL INTEGRITY.
- REPAIRS PER IPC-R-700 ARE ALLOWED.
- MODIFICATIONS TO THE ARTWORK, OTHER THAN THOSE DESCRIBED ON THE FABRICATION DRAWING, ARE NOT ALLOWED WITHOUT WRITTEN AUTHORIZATION.
- SEE DETAIL FOR HOLES THAT ARE TO BE FILLED WITH NON-CONDUCTIVE EPOXY FILL AND PLANARIZED, AND PLATED OVER.

6 LAYER STACKUP

- PRIMARY SILKSCREEN
- PRIMARY SOLDER MASK
- PRIMARY SIDE (LAYER 1)
- RETURN PLANE (LAYER 2)
- POWER PLANE (LAYER 3)
- POWER PLANE (LAYER 4)
- RETURN PLANE (LAYER 5)
- SECONDARY SIDE (LAYER 6)
- SECONDARY SOLDER MASK
- SECONDARY SILKSCREEN

NOMINAL FINISHED BOARD THICKNESS 0.062" +/- .007

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES

TOLERANCES

DECIMALS FRACTIONS ANGLES

.XX .XXX .010 .1/32 .2

.XXX .XXX .005

FABRICATION

APPROVAL DATE

DRAWN BY D.M.L. 14JUN10

DESIGNED

CHECKED

APPROVED

WFG ENGINEER

TITLE

AD9643 ENG.EVAL. PCB

SIZE FSCM NO DRAWING NUMBER REV

D 9643EE01 B

DO NOT SCALE DWG SCALE 2/1 SHEET 1 OF 1

HSC DIVISION 7910 TRIAD CTR. DR. GREENSBORO, NC 27409